ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	burn. Illinois. A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v s all lower	vithin the manufactu level materials for w	rer listed i which the n	tem. Note: nanufacture	if the item is an as or has engineering	sembly with low responsibility.	
			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials an					ials and M	ifg Informa	tion			
upplier Information														
Company name* Co			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi							ſ				2024-05-21			
ontact Name Title - Contact			et]	Phone - Contact*			Email - Contact*					
Product-Env-Stewards Product E			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - R			- Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Requester Item Number Mfr Item N		Number Mfr Item Name			Effective Date	Version	М	Ianufacturing Site		Weight*	UOM	Unit Type	
	AMIS30	MIS30532C5321RG 3,2A Stepper Driver		ver		2024-05-21	PHG			155.58	mg	Each		
Ianufacturing Proccess Informa	tion						-	·					· ·	
Terminal Plating / Grid Array M	aterial	ial Terminal Base Alloy J		J-STD-020 MSI	Rating	Peak Process Bo		Body Temperature Max Time at Peak		Temperat	ture Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	3			260 C 30		30	seconds 3					
omments														
TTENTION: MSL 3 Rated item require	es Bake and I	Dry Pack (after	electrical test)											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	13.42	mg	Supplier	Silicon (Si)	7440-21-3		13.42	mg	
Die Attach	4.09	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.818	mg	
			Supplier	Silver (Ag)	7440-22-4		3.272	mg	
Lead Frame	86.87	mg	Supplier	Zinc (Zn)	7440-66-6		0.0869	mg	
			Supplier	Iron (Fe)	7439-89-6		1.998	mg	
			Supplier	Copper (Cu)	7440-50-8		84.6983	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.0869	mg	
Mold Compound-Black	46.73	mg		Epoxy Phenol Resin	proprietary data		7.4768	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		39.2532	mg	
Plating	3.41	mg	Supplier	Tin (Sn)	7440-31-5		3.41	mg	
Wire Bond - Au	1.06	mg	Supplier	Gold (Au)	7440-57-5		1.06	mg	